

# SSR2N60B / SSU2N60B

## **600V N-Channel MOSFET**

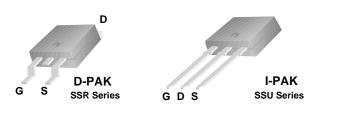
#### **General Description**

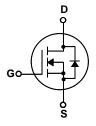
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switch mode power supplies.

#### **Features**

- 1.8A, 600V,  $R_{DS(on)} = 5.0\Omega \ @V_{GS} = 10 \ V$  Low gate charge ( typical 12.5 nC)
- Low Crss (typical 7.6 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability





# Absolute Maximum Ratings T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter		SSR2N60B / SSU2N60B	Units	
V <sub>DSS</sub>	Drain-Source Voltage		600	V	
I <sub>D</sub>	Drain Current - Continuous (T <sub>C</sub> = 25°	°C)	1.8	А	
	- Continuous (T <sub>C</sub> = 100	O°C)	1.1	Α	
I <sub>DM</sub>	Drain Current - Pulsed	(Note 1)	6.0	Α	
$V_{GSS}$	Gate-Source Voltage		± 30	V	
E <sub>AS</sub>	Single Pulsed Avalanche Energy	(Note 2)	120	mJ	
I <sub>AR</sub>	Avalanche Current	(Note 1)	1.8	Α	
E <sub>AR</sub>	Repetitive Avalanche Energy	(Note 1)	4.4	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	5.5	V/ns	
P <sub>D</sub>	Power Dissipation (T <sub>A</sub> = 25°C) *		2.5	W	
	Power Dissipation (T <sub>C</sub> = 25°C)		44	W	
	- Derate above 25°C		0.35	W/°C	
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Temperature Rar	nge	-55 to +150	°C	
TL	Maximum lead temperature for soldering 1/8" from case for 5 seconds	purposes,	300	°C	

# **Thermal Characteristics**

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		2.87	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient *		50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W

<sup>\*</sup> When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	600			V
ΔBV <sub>DSS</sub> / ΔΤ <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C		0.65		V/°C
I <sub>DSS</sub>	Zara Oata Vallana Basis Oamad	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V			10	μА
	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 480 V, T <sub>C</sub> = 125°C			100	μА
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	$V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$		ŀ	-100	nA
On Cha	racteristics					
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.9 A		3.8	5.0	Ω
g <sub>FS</sub>	Forward Transconductance	$V_{DS} = 40 \text{ V}, I_D = 0.9 \text{ A}$ (Note 4)		1.85		S
C <sub>iss</sub> C <sub>oss</sub> C <sub>rss</sub>	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		380 35 7.6	490 46 9.9	pF pF
	ing Characteristics			7.0	0.0	Pi
t <sub>d(on)</sub>	Turn-On Delay Time			16	40	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{DD} = 300 \text{ V}, I_{D} = 2.0 \text{ A},$		50	110	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	$R_G = 25 \Omega$		40	90	ns
t <sub>f</sub>	Turn-Off Fall Time	(Note 4, 5)		40	90	ns
Qg	Total Gate Charge	V <sub>DS</sub> = 480 V, I <sub>D</sub> = 2.0 A,		12.5	17	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		2.2		nC
Q <sub>gd</sub>	Gate-Drain Charge	(Note 4, 5)		5.4		nC
	ource Diode Characteristics a	nd Maximum Ratings				
I <sub>S</sub>	Maximum Continuous Drain-Source Did				1.8	Α
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode F	Forward Current			6.0	Α
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 1.8 \text{ A}$		-	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V, } I_{S} = 2.0 \text{ A,}$		250		ns
Q <sub>rr</sub>	Reverse Recovery Charge	$dI_{F} / dt = 100 \text{ A/}\mu\text{s}$ (Note 4)		1.31		μС

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 68mH, I<sub>AS</sub> = 2.0A, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25  $\Omega$ , Starting T<sub>J</sub> = 25°C 3. I<sub>SD</sub>  $\leq$  2.0A, di/dt  $\leq$  300A/μs, V<sub>DD</sub>  $\leq$  BV<sub>DSS</sub>, Starting T<sub>J</sub> = 25°C 4. Pulse Test : Pulse width  $\leq$  300 $\mu$ s, Duty cycle  $\leq$  2% 5. Essentially independent of operating temperature

# **Typical Characteristics**

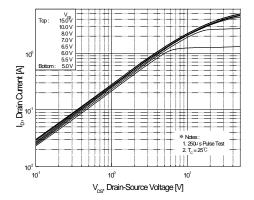


Figure 1. On-Region Characteristics

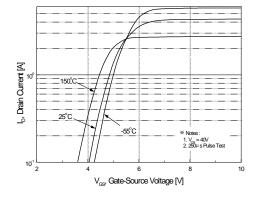


Figure 2. Transfer Characteristics

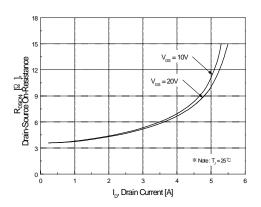


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

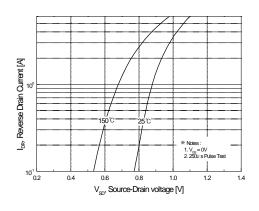


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

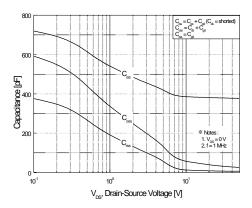


Figure 5. Capacitance Characteristics

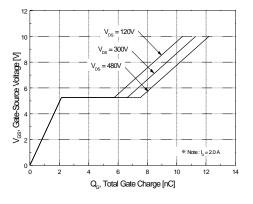


Figure 6. Gate Charge Characteristics

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# Typical Characteristics (Continued)

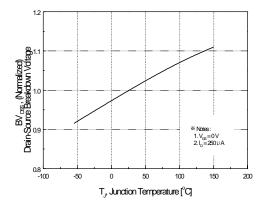


Figure 7. Breakdown Voltage Variation vs Temperature

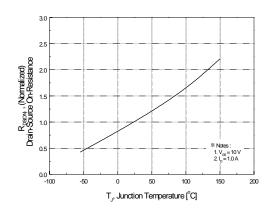


Figure 8. On-Resistance Variation vs Temperature

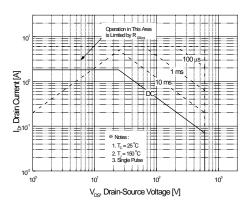


Figure 9. Maximum Safe Operating Area

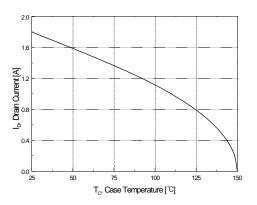


Figure 10. Maximum Drain Current vs Case Temperature

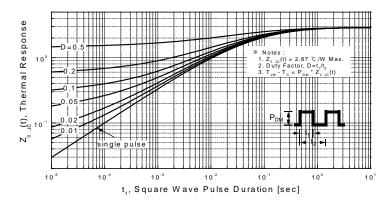
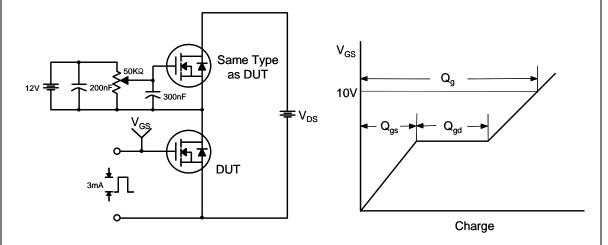
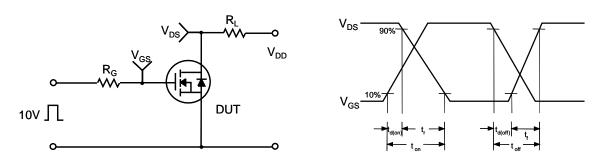


Figure 11. Transient Thermal Response Curve

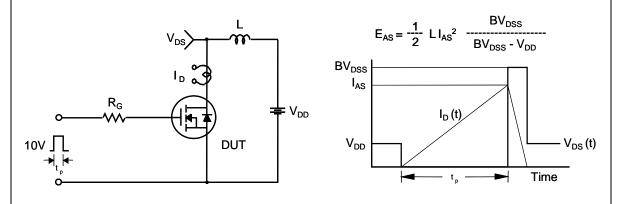
# **Gate Charge Test Circuit & Waveform**



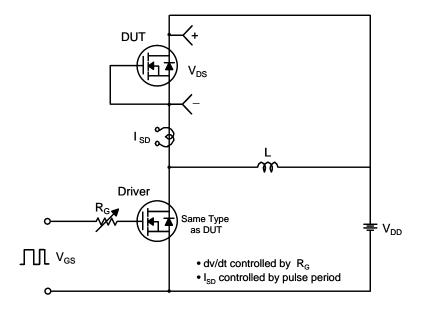
## **Resistive Switching Test Circuit & Waveforms**

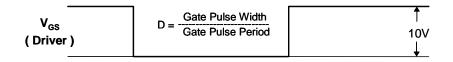


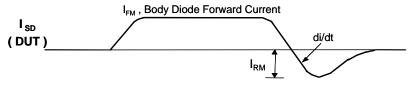
## **Unclamped Inductive Switching Test Circuit & Waveforms**



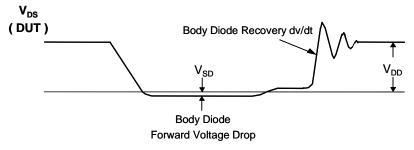
#### Peak Diode Recovery dv/dt Test Circuit & Waveforms

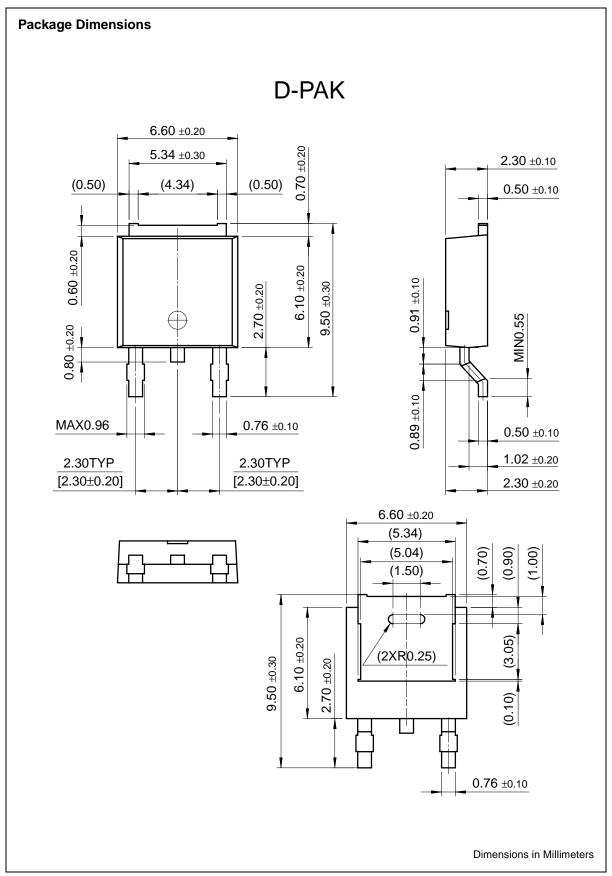


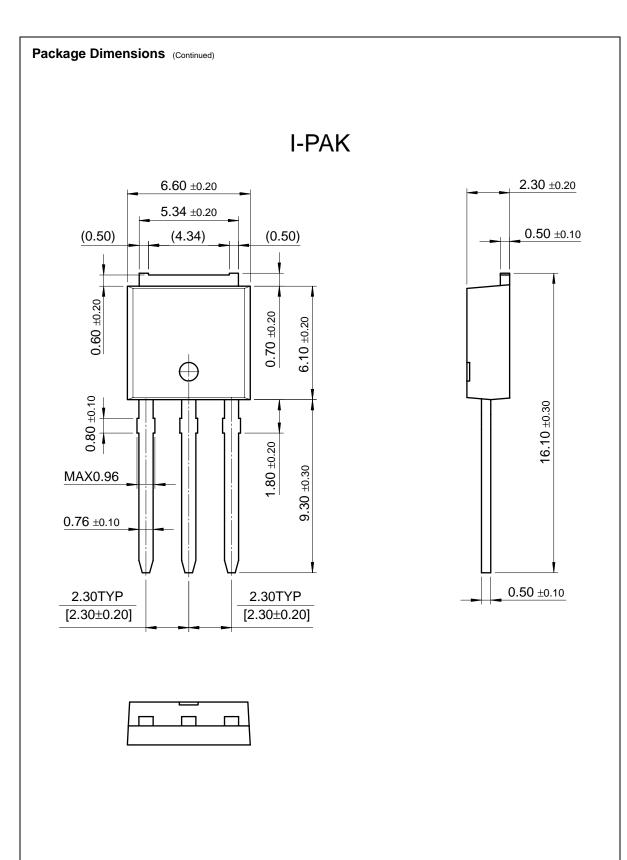




Body Diode Reverse Current







Dimensions in Millimeters

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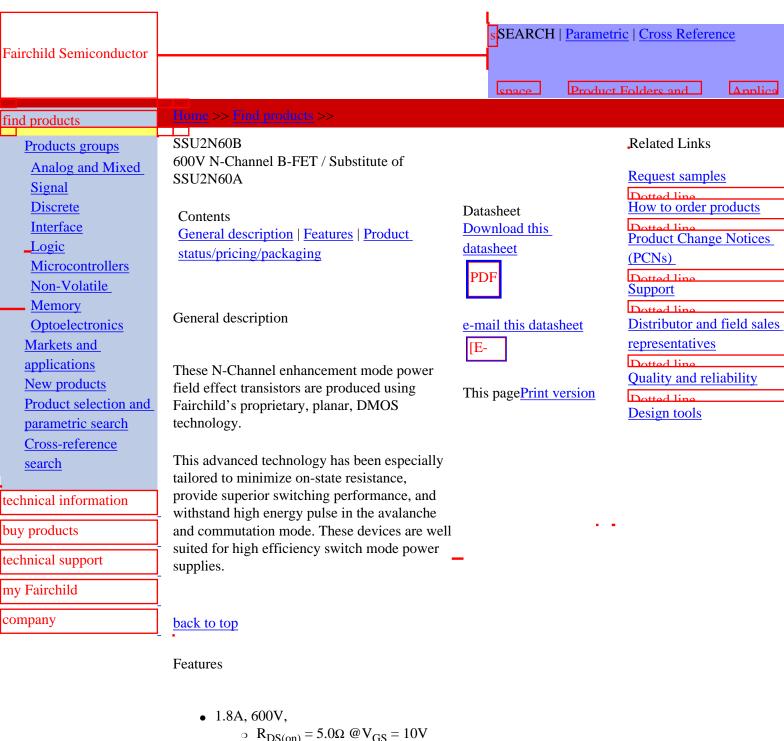
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- Low gate charge (typical 12.5 nC)
- Low Crss (typical 7.6 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

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Product status/pricing/packaging

Product   Product status   Pricing*   Package type   Leads   Packing	method
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Product Folder - Fairchild P/N SSU2N60B - 600V N-Channel B-FET / Substitute of SSU2N60A

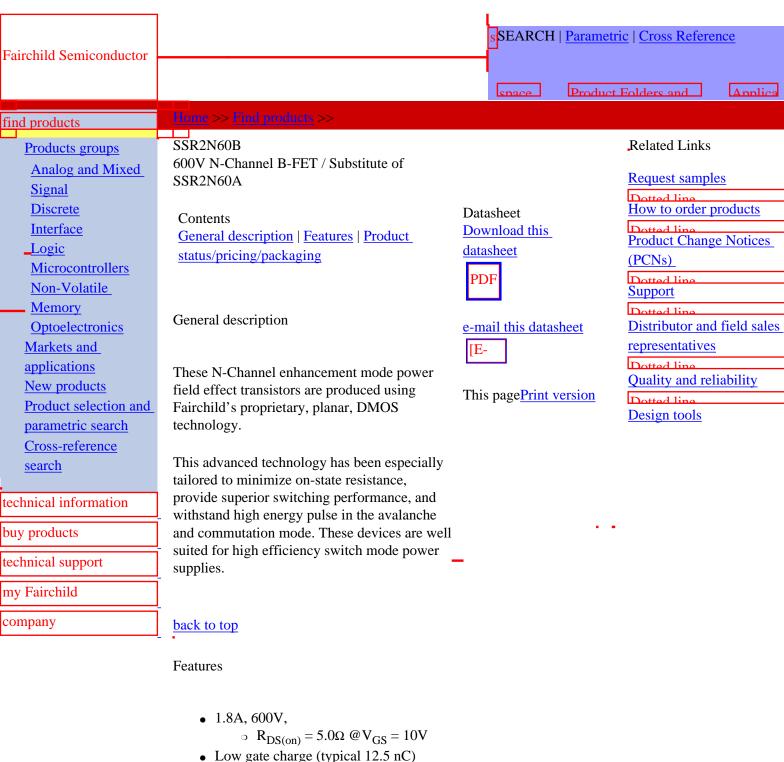
SSU2N60BTU	Full Production	\$0.451	TO-251(IPAK)	3	RAIL

<sup>\* 1,000</sup> piece Budgetary Pricing

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- Low Crss (typical 7.6 pF)
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Product	Product status	Pricing*	Package type	Leads	Packing method
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SSR2N60BTM	Full Production	\$0.451	TO-252(DPAK)	2	TAPE REEL
SSR2N60BTF	Full Production	\$0.451	TO-252(DPAK)	2	TAPE REEL

<sup>\* 1,000</sup> piece Budgetary Pricing

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